



Product/Process Change Notice - PCN 16_0230 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Assembly Transfer of Select LFCSP Products to ASE Korea
Publication Date: 25-Oct-2016
Effectivity Date: 23-Jan-2017 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI is transferring to subcontractor ASE Korea for assembly manufacturing of select LFCSP products. The package outline dimensions, wire diameter of each product will be maintained. ADI has qualified ASE Korea's BOM (Bill of Materials). The mold compound is changing from Sumitomo G770 to Sumitomo G700. Die attach epoxy is changing from Able8290 and Able3230 to EN4900GC for 5x5 LFCSP devices. See BOM attachment for details. The package outline exposed pad dimensions are changing for 3x3mm 8LD/16LD, 4x4mm 16LD/20LD/24LD, 5x5mm 32LD. See POD attachment for details.

Reason For Change

ADI's current Assembly supplier STATS ChipPAC China is relocating their factory by end of September 2017. In this regard, the affected products currently assembled in that facility will be transferred to ASE Korea to ensure continuous supply of products. ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

There will be no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled from the transfer will be identified by assembly lot and the country of origin.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Results Summary.

Comments

During transition to the new assembly site, products will be Assembled from the either current or the new assembly site. The customers may receive products that are assembled at SCC or assembled at AEK. This notification applies to all packing/reel options.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_16_0230_Rev_-_Qual Results Summary for LFCSP.pdf

Attachment 2: Type: Detailed Change Description

ADI_PCN_16_0230_Rev_-_BOM Change Description.pptx

Attachment 3: Type: Detailed Change Description

ADI_PCN_16_0230_Rev_-_POD Change Description.pptx

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (31)

AD5421 / AD5421ACPZ-REEL7	AD5421 / AD5421BCPZ-REEL7	AD7196 / AD7196BCPZ-RL	AD7196 / AD7196BCPZ-RL7	AD8141 / AD8141ACPZ-R7
AD8142 / AD45237-RL	AD8142 / AD8142ACPZ-R7	AD8142 / AD8142ACPZ-RL	AD8436 / AD8436ACPZ-R7	AD8436 / AD8436ACPZ-RL
AD8436 / AD8436ACPZ-WP	AD8436 / AD8436JCPZ-R7	AD8436 / AD8436JCPZ-RL	AD8475 / AD8475ACPZ-R7	AD8475 / AD8475ACPZ-RL
AD9508 / AD9508BCPZ	AD9508 / AD9508BCPZ-REEL7	ADA4896-2 / AD45253-RL	ADA4896-2 / ADA4896-2ACPZ-R2	ADA4896-2 / ADA4896-2ACPZ-R7
ADA4896-2 / ADA4896-2ACPZ-RL	ADF4158 / ADF4158CCPZ	ADF4158 / ADF4158CCPZ-RL7	ADL5303 / ADL5303ACPZ-R2	ADL5303 / ADL5303ACPZ-R7
ADL5303 / ADL5303ACPZ-RL	ADL5565 / ADL5565ACPZ-R7	ADLD8403 / ADLD8403ACPZ-R2	ADLD8403 / ADLD8403ACPZ-R7	ADLD8403 / ADLD8403ACPZ-RL
ADLD8404 / AD45224-R7				

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	25-Oct-2016	23-Jan-2017	Initial Release

Analog Devices, Inc.

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